

XR-DIMM™ Rugged Memory

Industry Standard



Due to the demanding needs of ruggedized embedded applications, Samtec has worked with SFF-SIG to create a new XR-DIMM™ Rugged Memory Specification. The new XR-DIMM™ pinout follows closely to the JEDEC DDR3 defined SO-DIMM pin definition. These XR-DIMM™ memory modules are ideal for ruggedized small form factor single board computing applications. Standardized around the 38mm X 67.5mm footprint, the XR-DIMM™ is smaller and more rugged than the common commercial grade SO-DIMM socket. It is currently defined for DDR3 as well as optional ECC & SATA-2 SSD flash memory.

Available in 5mm, 11mm or 16mm for mezzanine stacks; the 240 pin Samtec BTH/ BSH connector in the XR-DIMM™ form factor exceeds the demands of ANSI/VITA 47-2005 (R2007) specification for heavy vibration & shock.

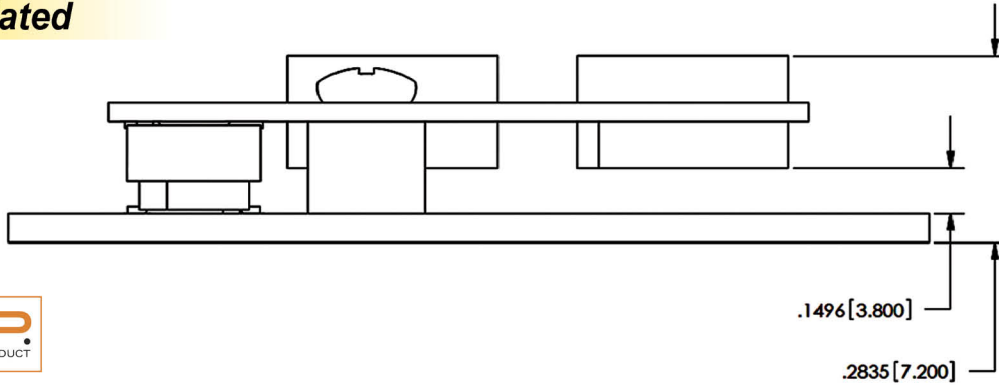
For additional information contact: Standards@samtec.com

- XR-DIMM™: Extreme Ruggedized Dual In-line Memory Module
- SFF-SIG & XR-DIMM™ are trademarks of Small Form Factor Special Interest Group

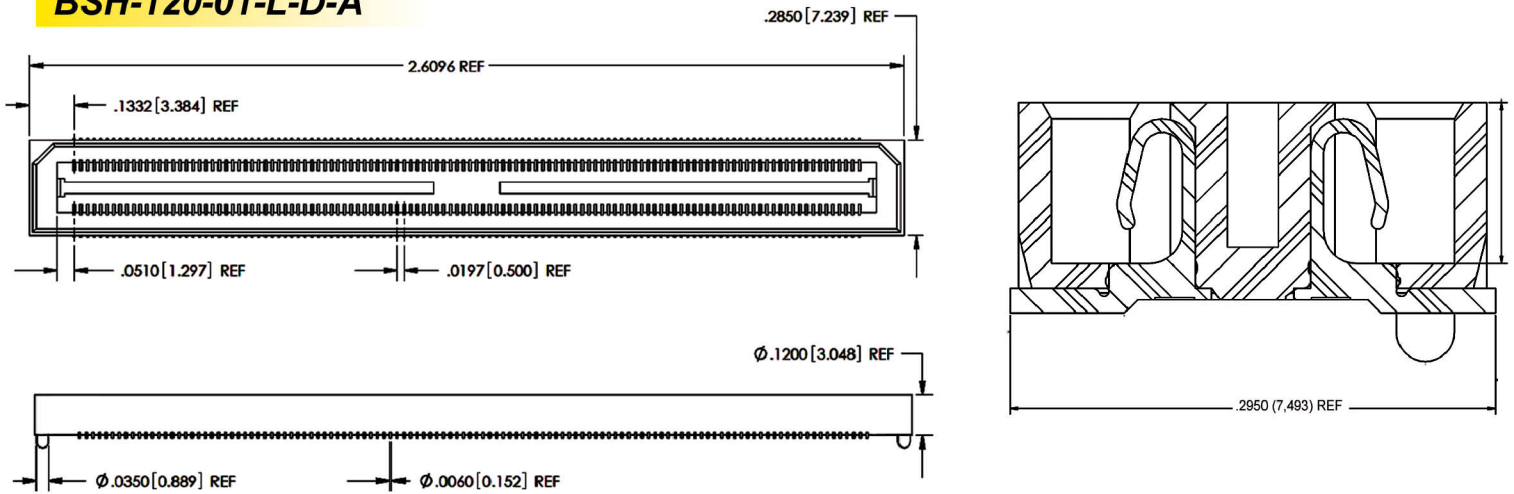
XR-DIMM™ Rugged Memory



BSH / BTH Mated



BSH-120-01-L-D-A



BTH-120-01-L-D-A

